

MB05F THRU MB10F

0.8A Miniature Glass Passivated Single-Phase Surface Mount Bridge Rectifiers-50-1000V

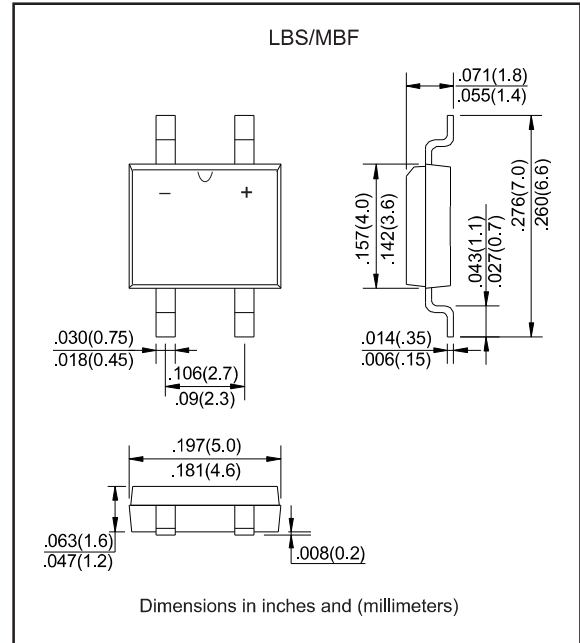
Features

- Surge overload ratings to 30 amperes peak.
- Save space on printed circuit board.
- Ideal for automated replacement.
- Reliable low cost construction utilizing molded plastic technology results in inexpensive product.
- Glass passivated chip junctions.
- Lead-free parts meet RoHS requirements.
- UL recognized file # E321971
- Suffix "-H" indicates Halogen free part, ex. MB05F -H.

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, LBS/MBF
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : marked on body
- Mounting Position : Any

Package outline



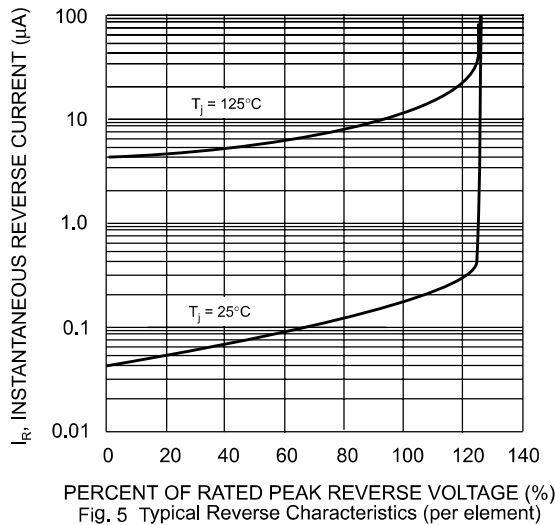
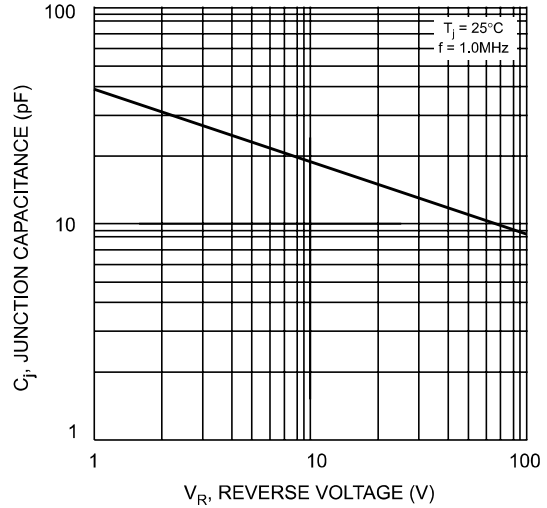
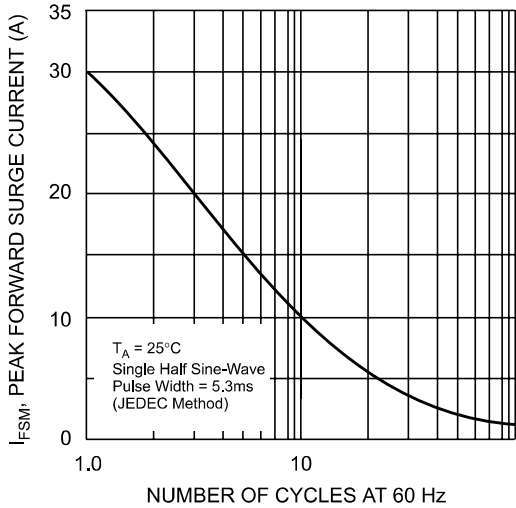
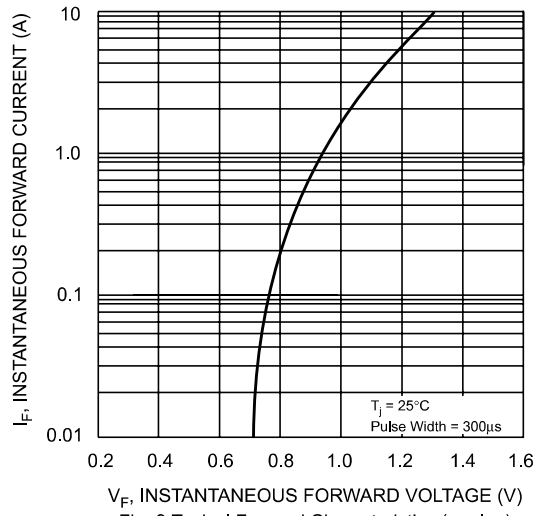
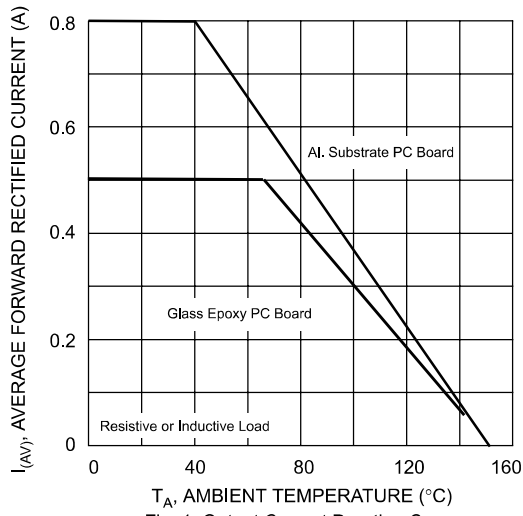
Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	On glass-epoxy P.C.B. On aluminum substrate	I _O			0.5 0.8	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I _{FSM}			30	A
Reverse current	V _R = V _{RRM} T _J = 25°C	I _R			5.0	uA
	V _R = V _{RRM} T _J = 125°C				200	
Thermal resistance	Junction to ambient	R _{θJA}		60		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C _J		13		pF
Storage temperature		T _{STG}	-55		+150	°C

SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	V _F ^{*4} (V)	Operating temperature T _J , (°C)
MB05F	50	35	50	1.00	-55 to +150
MB1F	100	70	100		
MB2F	200	140	200		
MB4F	400	280	400		
MB6F	600	420	600		
MB8F	800	560	800		
MB10F	1000	700	1000		

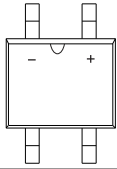
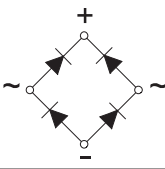
- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage per element at 0.8A peak

Rating and characteristic curves (MB05F THRU MB10F)

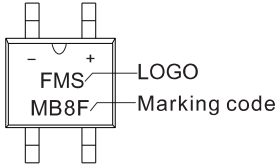
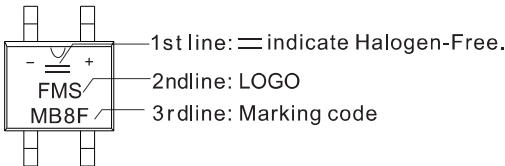


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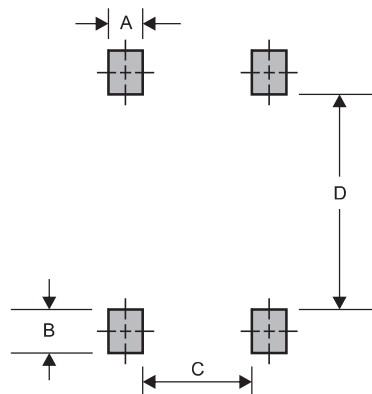
Pinning information

Simplified outline	Symbol
	

Marking

Type number	Marking code	Example	
MB05F MB1F MB2F MB4F MB6F MB8F MB10F	MB05F MB1F MB2F MB4F MB6F MB8F MB10F	1. For Halogen Device 	2. For Halogen-free Device 

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
LBS/MBF	0.023 (0.58)	0.030 (0.76)	0.070 (1.78)	0.226 (5.75)